

SNx4AC373 3 ステート出力、オクタル D タイプ・トランスペアレント・ラッチ

1 特長

- 2V~6V の V_{CC} で動作
- 6V までの入力電圧に対応
- 最大 t_{pd} 9.5ns (5V 時)
- 3 ステート非反転出力はバスラインを直接駆動
- 読み込み時の完全並列アクセス

2 概要

これらの 8 ビット ラッチは、大きな容量性負荷または比較的低インピーダンスの負荷の駆動用に設計された 3 ステート出力を備えています。本デバイスは、バッファレジスタ、I/O ポート、双方向バスドライバ、作業レジスタの実装に特に適しています。

製品情報

部品番号	パッケージ ⁽¹⁾	パッケージサイズ ⁽²⁾	本体サイズ ⁽³⁾
SNx4AC373	DB (SSOP, 20)	7.2mm × 7.8mm	7.2mm × 5.30mm
	DW (SOIC, 20)	12.80mm × 10.3mm	12.80mm × 7.50mm
	N (PDIP, 20)	24.33mm × 9.4mm	24.33mm × 6.35mm
	NS (SOP, 20)	12.6mm × 7.8mm	12.6mm × 5.3mm
	PW (TSSOP, 20)	6.50mm × 6.4mm	6.50mm × 4.40mm

- (1) 詳細については、[セクション 10](#) を参照してください。
- (2) パッケージサイズ (長さ×幅) は公称値であり、該当する場合はピンも含まれます。
- (3) 本体サイズ (長さ×幅) は公称値であり、ピンは含まれません。

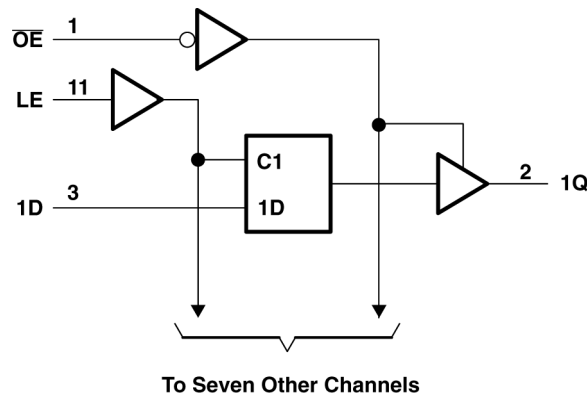


Table of Contents

1 特長	1	6.2 Functional Block Diagram.....	8
2 概要	1	6.3 Device Functional Modes.....	8
3 Pin Configuration and Functions	3	7 Application and Implementation	9
4 Specifications	4	7.1 Power Supply Recommendations.....	9
4.1 Absolute Maximum Ratings.....	4	7.2 Layout.....	9
4.2 Recommended Operating Conditions.....	4	8 Device and Documentation Support	10
4.3 Thermal Information.....	5	8.1 Documentation Support.....	10
4.4 Electrical Characteristics.....	5	8.2 ドキュメントの更新通知を受け取る方法.....	10
4.5 Timing Requirements, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	5	8.3 サポート・リソース.....	10
4.6 Timing Requirements, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	5	8.4 Trademarks.....	10
4.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	6	8.5 静電気放電に関する注意事項.....	10
4.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	6	8.6 用語集.....	10
4.9 Operating Characteristics.....	6	9 Revision History	10
5 Parameter Measurement Information	7	10 Mechanical, Packaging, and Orderable Information	12
6 Detailed Description	8		
6.1 Overview.....	8		

3 Pin Configuration and Functions

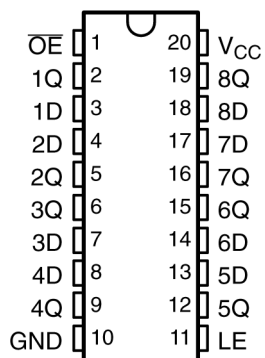


図 3-1. SN54AC373 J or W Package; SN74AC373 DB, DW, N, NS, or PW Package (Top View)

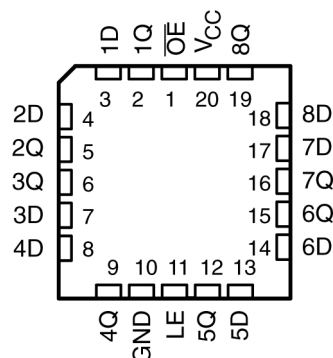


図 3-2. SN54AC373 FK Package (Top View)

表 3-1. Pin Functions

NO.	PIN		TYPE	DESCRIPTION
	SSOP, TVSOP, SOIC, SO, or TSSOP	VQFN		
1	OE	OE	I	Output Enable
2	1Q	1Q	O	1Q Output
3	1D	1D	I	1D Input
4	2D	2D	I	2D Input
5	2Q	2Q	O	2Q Output
6	3Q	3Q	O	3Q Output
7	3D	3D	I	3D Input
8	4D	4D	I	4D Input
9	4Q	4Q	O	4Q Output
10	GND	GND	—	Ground Pin
11	LE	LE	I	Latch Enable
12	5Q	5Q	O	5Q Output
13	5D	5D	I	5D Input
14	6D	6D	I	6D Input
15	6Q	6Q	O	6Q Output
16	7Q	7Q	O	7Q Output
17	7D	7D	I	7D Input
18	8D	8D	I	8D Input
19	8Q	8Q	O	8Q Output
20	V _{CC}	V _{CC}	—	Power Pin
—	—	Thermal Pad	—	Thermal Pad, normally tied to GND

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)¹

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I ¹	Input voltage range	-0.5	$V_{CC} + 0.5$	V
V_O ¹	Output voltage range	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$(V_I < 0 \text{ or } V_I > V_{CC})$		±20 mA
I_{OK}	Output clamp current	$(V_O < 0 \text{ or } V_O > V_{CC})$		±20 mA
I_O	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		±50 mA
	Continuous current through V_{CC} or GND			±200 mA
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)¹

			SN54AC373		SN74AC373		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	6	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 4.5 V	3.15		3.15		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V		0.9		0.9	V
		V _{CC} = 4.5V		1.35		1.35	
		V _{CC} = 5.5 V		1.65		1.65	
V _I	Input voltage		0	V _{CC}	0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V		-12		-12	mA
		V _{CC} = 4.5 V		-24		-24	
		V _{CC} = 5.5 V		-24		-24	
I _{OL}	Low-level output current	V _{CC} = 3 V		12		12	mA
		V _{CC} = 4.5 V		24		24	
		V _{CC} = 5.5 V		24		24	
Δt/Δv	Input transition rise or fall rate			8		8	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to for proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.3 Thermal Information

THERMAL METRIC ⁽¹⁾	SNx4AC373					UNIT	
	DB (SSOP)	DW (SOIC)	N	NS (SO)	PW (TSSOP)		
	20 PINS						
R _{θJA}	Junction-to-ambient thermal resistance	70	101.2	69	60	126.2	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.46		
		4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
V _{OL}	I _{OL} = 50μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		80		40	μA
C _i	V _I = V _{CC} or GND	5 V			4.5					pF

4.5 Timing Requirements, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

		T _A = 25°C		SN54AC373		SN74AC373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	5.5		6.5		6		ns
t _{su}	Setup time, data before LE ↓	5.5		6.5		6		ns
t _h	Hold time, data after LE ↓	1		1		1		ns

4.6 Timing Requirements, V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

		T _A = 25°C		SN54AC373		SN74AC373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	4		5		4.5		ns
t _{su}	Setup time, data before LE ↓	4		5		4.5		ns
t _h	Hold time, data after LE ↓	1		1		1		ns

4.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.5	10	13.5	1	16.5	1.5	15	ns
t_{PHL}			1.5	9.5	13.0	1	16	1.5	14.5	
t_{PLH}	LE	Q	1.5	10	13.5	1	16.5	1.5	15	ns
t_{PHL}			1.5	9.5	12.5	1	15	1.5	14	
t_{PZH}	$\overline{OE}$	Q	1.5	9	11.5	1	14	1	13	ns
t_{PZL}			1.5	8.5	11.5	1	13.5	1	13	
t_{PHZ}	$\overline{OE}$	Q	1.5	10	12.5	1	16	1	14.5	ns
t_{PLZ}			1.5	8	11.5	1	13	1	12.5	

4.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

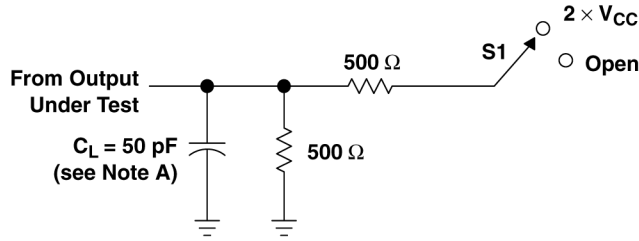
PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.5	7	9.5	1	11.5	1.5	10.5	ns
t_{PHL}			1.5	7	9.5	1	11.5	1.5	10.5	
t_{PLH}	LE	Q	1.5	7.5	9.5	1	12	1.5	10.5	ns
t_{PHL}			1.5	7	9.5	1	11	1.5	10.5	
t_{PZH}	$\overline{OE}$	Q	1.5	7	8.5	1	10.5	1	9.5	ns
t_{PZL}			1.5	6.5	8.5	1	10	1	9.5	
t_{PHZ}	$\overline{OE}$	Q	1.5	8	11	1	13.5	1	12.5	ns
t_{PLZ}			1.5	6.5	8.5	1	10.5	1	10	

4.9 Operating Characteristics

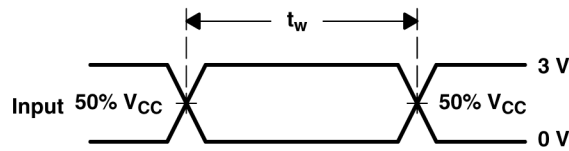
$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$	$f = 1\text{ MHz}$	40	pF

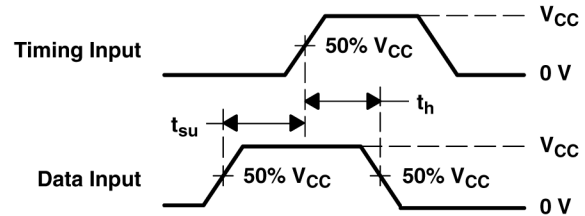
5 Parameter Measurement Information



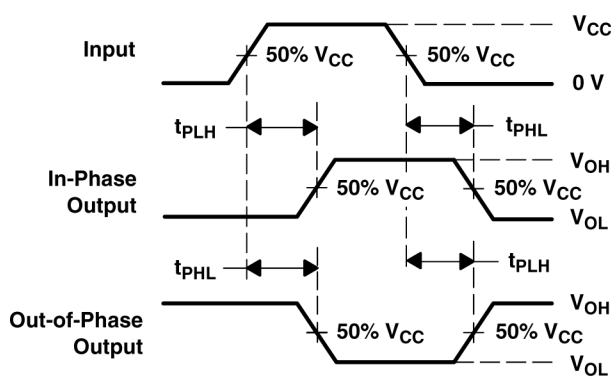
LOAD CIRCUIT



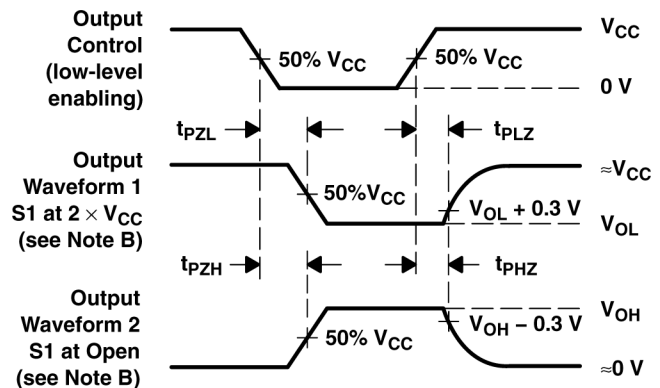
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

图 5-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 $\times$ V_{CC}
t_{PHZ}/t_{PZH}	Open

7 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

7.1 Power Supply Recommendations

7.2 Layout

7.2.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Layout Diagram](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

7.2.2 Layout Example

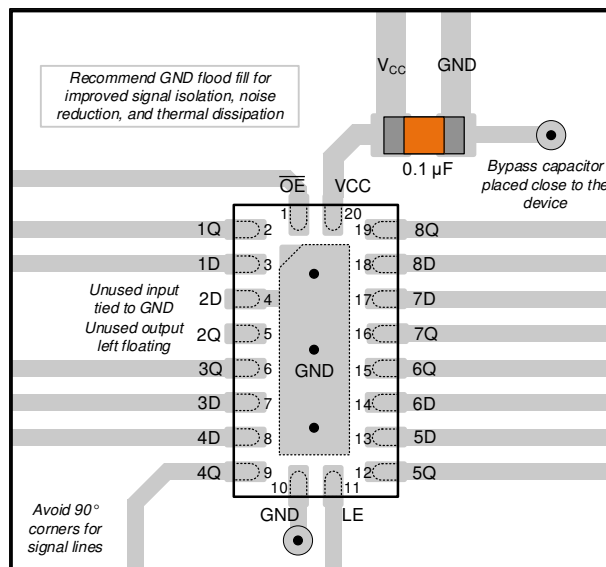


図 7-1. Layout example for the SNx4AC373

8 Device and Documentation Support

8.1 Documentation Support

8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AC373	Click here	Click here	Click here	Click here	Click here
SN74AC373	Click here	Click here	Click here	Click here	Click here

8.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

8.3 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの[使用条件](#)を参照してください。

8.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

8.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

8.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

9 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision E (August 2023) to Revision F (February 2024)	Page
• Updated RθJA values: DW = 58 to 101.2, PW = 83 to 126.2, all values in °C/W	5
• Added <i>Application and Implementation</i> section.....	9

Changes from Revision D (October 2003) to Revision E (August 2023)

Page

- 「製品情報」表、「ピンの機能」表、「熱に関する情報」表、「デバイスの機能モード」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加 **1**

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-87555012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87555012A SNJ54AC 373FK
5962-8755501RA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501RA SNJ54AC373J
5962-8755501SA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501SA SNJ54AC373W
5962-8755501VSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501VS A SNV54AC373W
5962-8755501VSA.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501VS A SNV54AC373W
SN74AC373DBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373DBR.A	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373DWRE4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373N	NRND	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC373N
SN74AC373N.A	NRND	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC373N
SN74AC373NE4	NRND	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC373N
SN74AC373NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373NSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373PW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 85	AC373
SN74AC373PWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SN74AC373PWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC373
SNJ54AC373FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87555012A SNJ54AC 373FK

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54AC373FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-87555012A SNJ54AC 373FK
SNJ54AC373J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501RA SNJ54AC373J
SNJ54AC373J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501RA SNJ54AC373J
SNJ54AC373W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501SA SNJ54AC373W
SNJ54AC373W.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755501SA SNJ54AC373W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AC373, SN54AC373-SP, SN74AC373 :

- Catalog : [SN74AC373, SN54AC373](#)
- Military : [SN54AC373](#)
- Space : [SN54AC373-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC373DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC373DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AC373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AC373NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AC373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC373DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74AC373DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC373DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC373NSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74AC373PWR	TSSOP	PW	20	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87555012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8755501SA	W	CFP	20	25	506.98	26.16	6220	NA
5962-8755501VSA	W	CFP	20	25	506.98	26.16	6220	NA
5962-8755501VSA.A	W	CFP	20	25	506.98	26.16	6220	NA
SN74AC373N	N	PDIP	20	20	506	13.97	11230	4.32
SN74AC373N.A	N	PDIP	20	20	506	13.97	11230	4.32
SN74AC373NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54AC373FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC373FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC373W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54AC373W.A	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

NOTES:

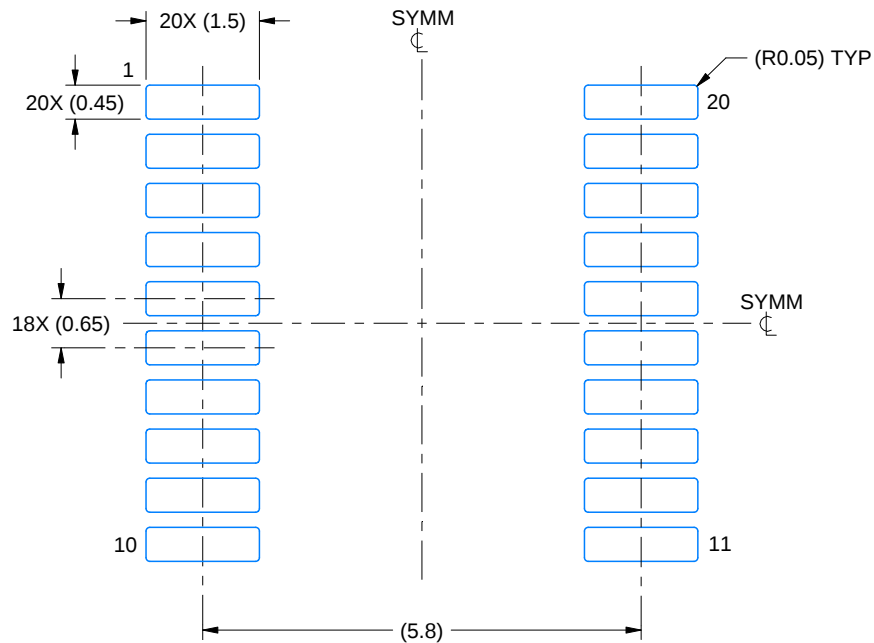
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

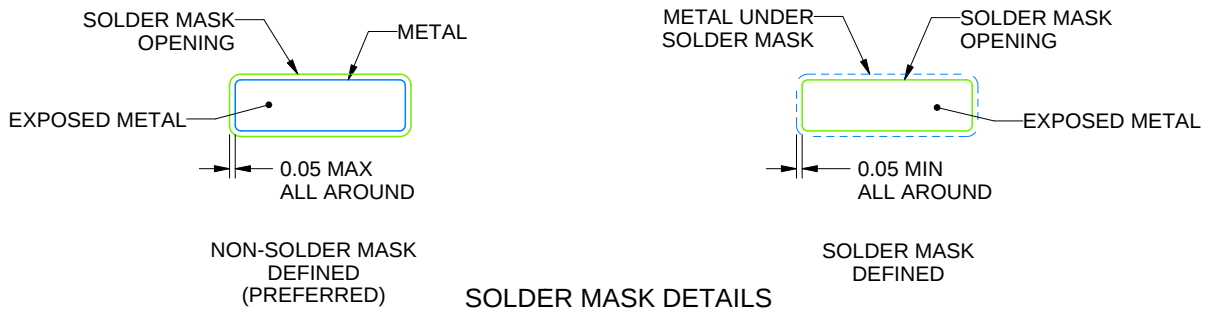
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

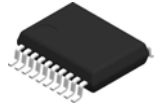


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4214851/B 08/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



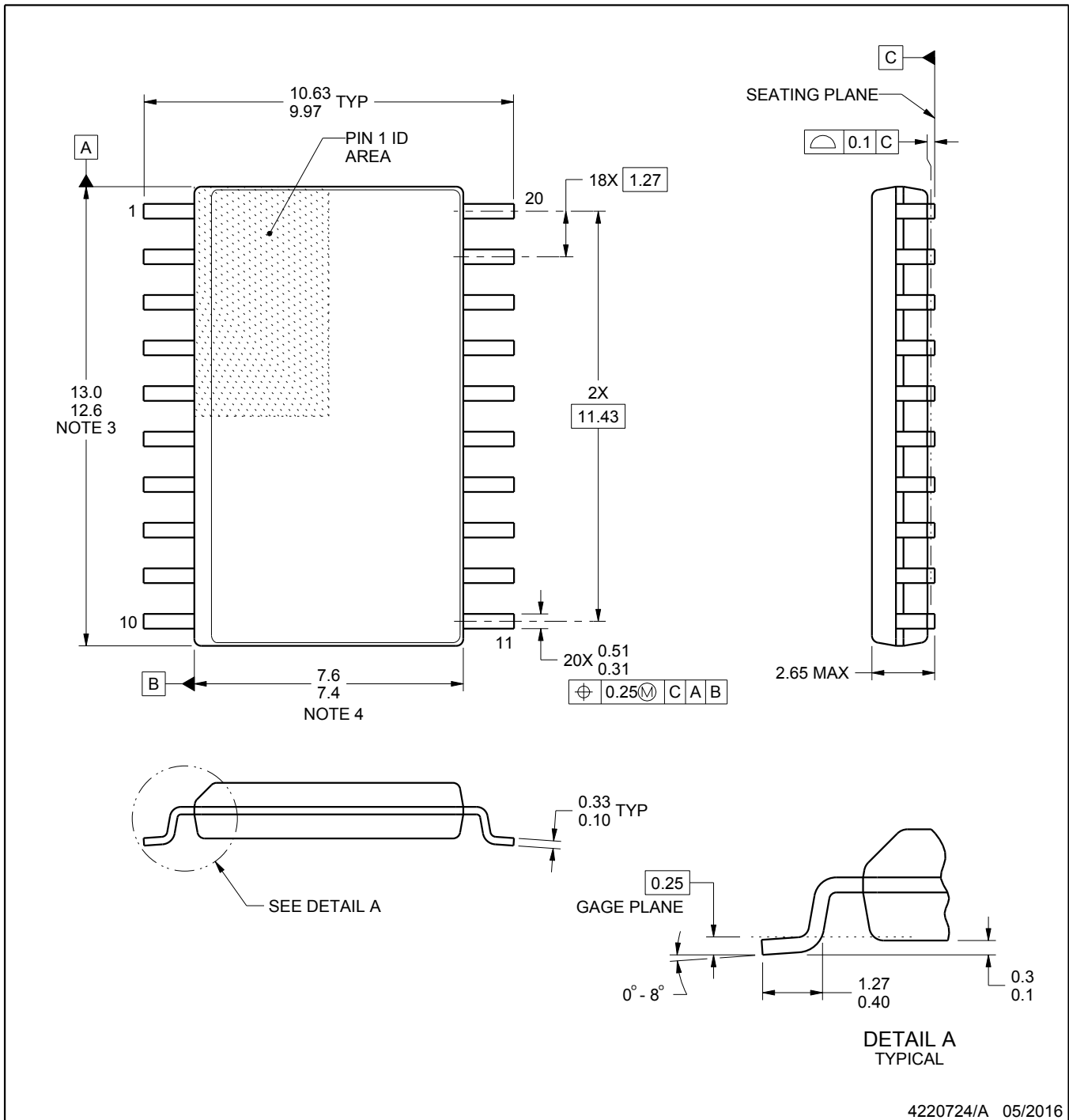
PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

NOTES:

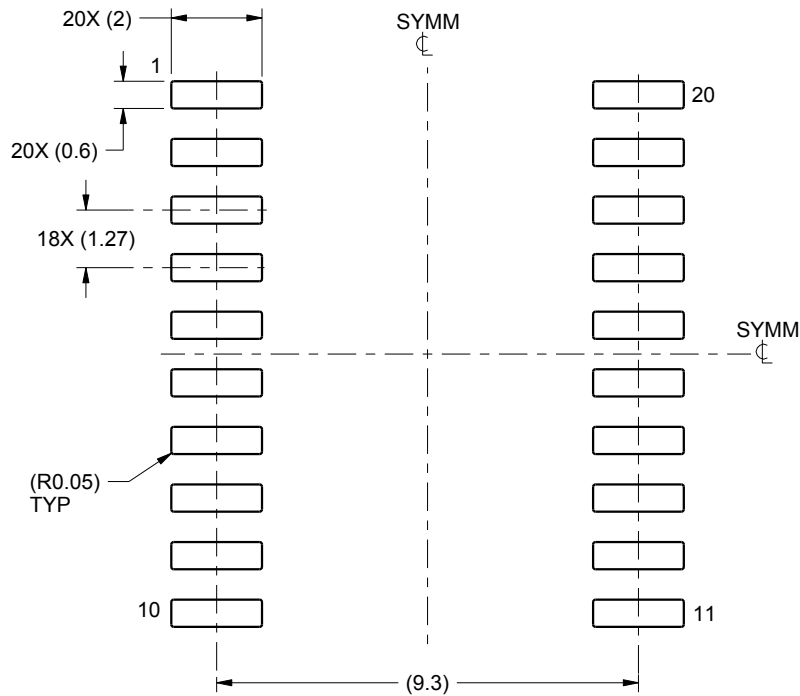
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

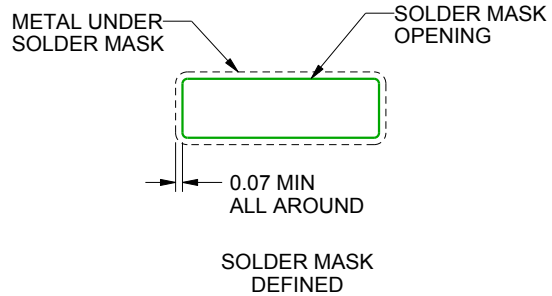
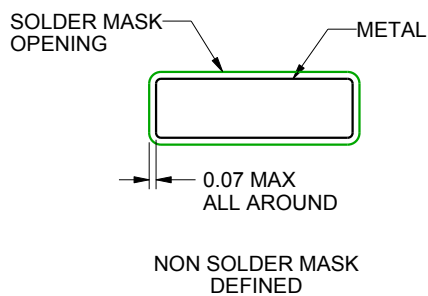
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含みいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、TI は一切の責任を拒否します。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、[TI の総合的な品質ガイドライン](#)、[ti.com](https://www.ti.com) または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

Copyright © 2026, Texas Instruments Incorporated

最終更新日：2025 年 10 月